

6/8inch Dielectric Etcher

Model: SA-NMC508SDH/SDL

SA-NMC508SDH/SDL are mature 6/8-inch dielectric etchers for logic, SiC power and MEMS manufacturing, processing SiO₂ and SiNx for FEOL and BEOL steps. Featuring adjustable dual-zone gas injection and dual-zone ESC, the tools realize excellent wafer uniformity. SDL boasts higher etch rate while SDH cuts ownership cost, both with long MTBC and stable mass-production capability.



Feature

- Better Temp U%
- Clean Mode
- High Precision Control
- Better Roughness
- Short Maintenance Time

Application

- Logic
- Power
- Si/SiC
- MEMS
- GaN

Specifications:

Parameter	SDH	SDL
Wafer Size	6/8inch	
Etching Materials	Dielectric SiO ₂ /SiNx/SiON	
Processes	FEOL/BEOL(HM/CT/Spacer/Via/PAD)	
SHD	Si	Al-Y ₂ O ₃ coating
Gas Injection	Dual zone inject(10-90% adj)	
Temp Control	Chiller	
Cathode	Dual zone ESC	
Process Mode	-	Clean Mode
ER	> 4500 A/min	>6000 A/min
Sidewall Roughness	< 1 nm	-
U%	WIW < 3% @ EE3mm WTW < 3%	
WPH	~ 10 @15K	12 @10K
COC	1	
MTTR	< 1h	-
MTBC	> 200 RFh	> 150RFh
W×L×H	3253×3279×2339 mm	

Principle:

